

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

DSS32-MS THRU DSS310-MS

Product specification


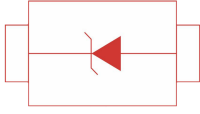
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High forward surge current capability
- High temperature soldering guaranteed:
250°C/10 seconds, 0.375(9.5mm) lead length,
5 lbs. (2.3kg) tension

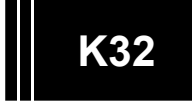
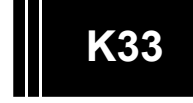
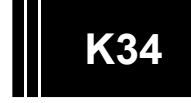
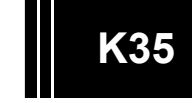

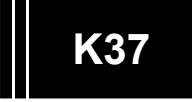

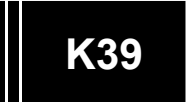
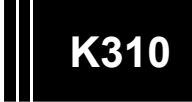
MECHANICAL DATA

- Case: JEDEC SOD-123FL molded plastic body over passivated junction
- Terminals : Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight: 0.0007 ounce, 0.02 grams

Reference News

SOD-123FL	Schematic Diagram
	

Marking

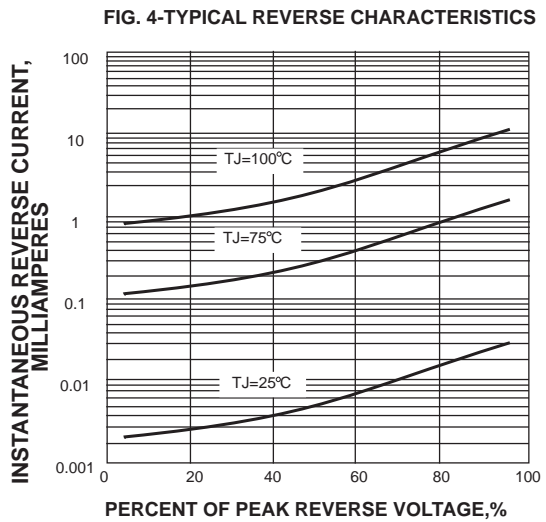
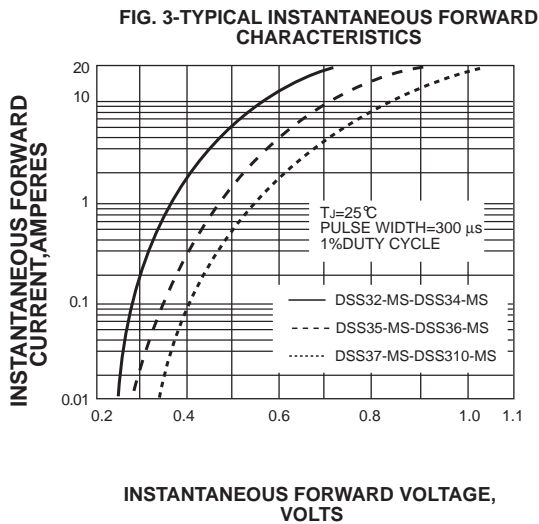
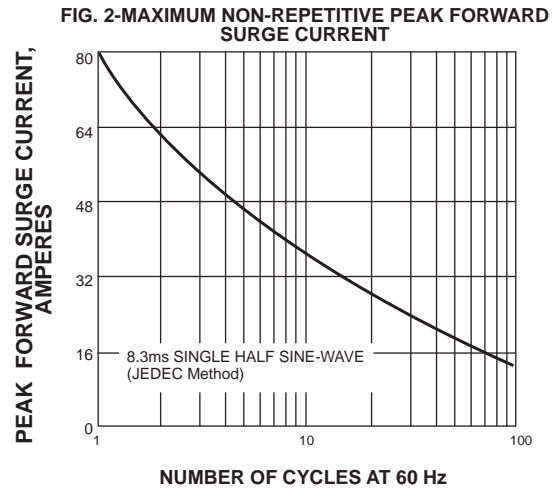
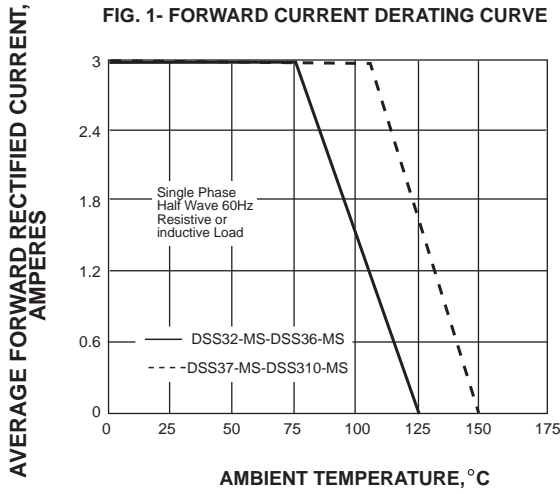
DSS32-MS	DSS33-MS	DSS34-MS	DSS35-MS	DSS36-MS
				
DSS37-MS	DSS38-MS	DSS39-MS	DSS310-MS	
				

Maximum Ratings and Electrical Characteristics

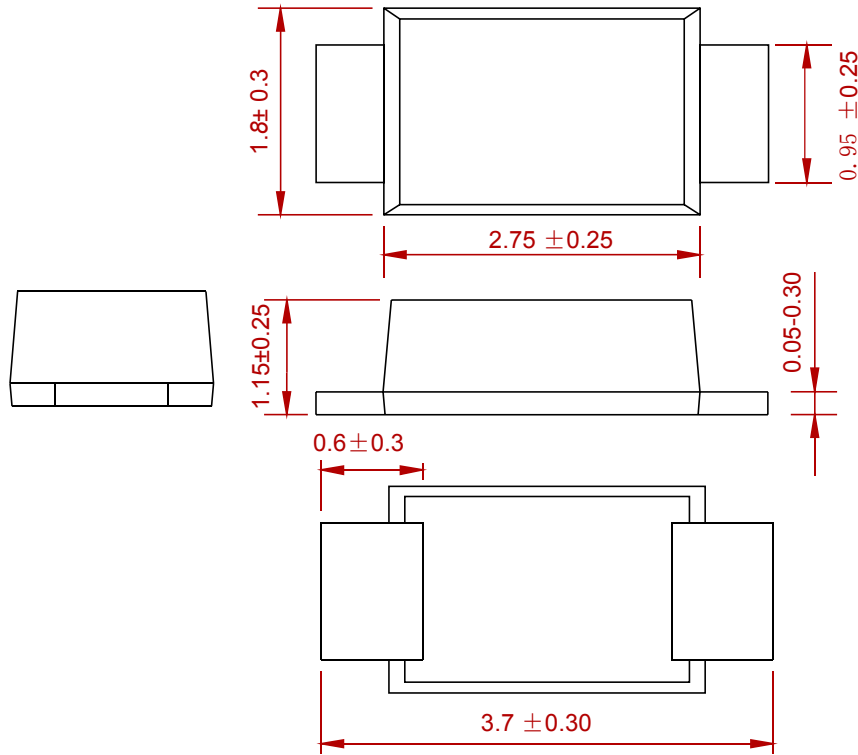
TA = 25°C unless otherwise specified
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	DSS32 -MS	DSS33 -MS	DSS34 -MS	DSS35 -MS	DSS36 -MS	DSS37 -MS	DSS38 -MS	DSS39 -MS	DSS310 -MS	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	70	80	90	100	Volts
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	49	56	63	70	Volts
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	70	80	90	100	Volts
Maximum average forward rectified current	I _(AV)	3.0									Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	80.0									Amps
Maximum instantaneous forward voltage at 3.0A Maximum DC reverse current	V _F	0.52	0.55		0.70		0.85			Volts	
at rated DC blocking voltage T _A =25°C T _A =100°C	I _R	0.5									mA
		20.0					10.0				
Operating junction temperature range	T _J	-50 to +125					-50 to +150				°C
Storage temperature range	T _{STG}	-50 to +150									°C

RATINGS AND CHARACTERISTIC CURVES DSS32-MS THRU DSS310-MS

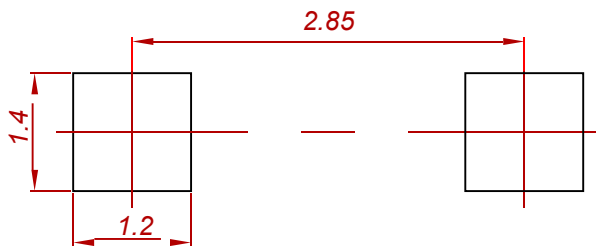


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DSS32-MS THRU DSS310-MS	SOD-123FL	3000

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